**Product / Process Change Notice**

**Parts Affected:**

General purpose and ultrafast recovery rectifiers manufactured in the SMA, SMAFL, SMB, SMC, and DO-201 cases.

**Extent of Change:**

Addition of new wafer fab.

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure undisrupted product supply, an additional wafer fabrication site is being added for the referenced product families. Product specifications, quality and reliability are not impacted by this addition.

**Effect of Change:**

This addition does not affect the fit, form or function of the devices.

**Qualification:**

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| **Test** | **Condition** | **Duration** | **Failure rate** |
| **Pre Conditioning(P.C) (SMD qualification parts before test T.C., A.C, T.H.B , I.O.L and R.S.H）** | 1. TCT -55~+150 ℃ ,5 cycle  2. Bake 125 +5/-0 ℃ , 24hours  3. Temperature humidity 85℃/85%RH, 168hours  4. Reflow 3 times | 1 Cycle | 0/77  3 Lots |
| **Temperature Cycling (T.C.)** | TA= -55+0℃/-10℃ 10min(Min)  TA= +150+15℃/-0℃ 10min(Min)  Transfer time less than 1min.  The load should reach temp. within 15min | 1000 Cycles | 0/77  3 Lots |
| **High Temperature Reverse Bias (HTRB)** | TA=140℃, VR=100%VB  DC supply | 1000 Hours | 0/77  3 Lots |
| **Resistance to Solder Heat (R.S.H.)** | T =260°C ±5°C Dwell time = 10 sec. | 1 Cycle | 0/30  3 Lots |
| **Intermittent**  **Forward**  **Operation Life (I.O.L.)** | I=1.0 × IF DC supply  On time: 2mins at least,  Off time: 2mins at least | 15,000 Cycles | 0/77  3 Lots |
| **Autoclave (A.C.)** | Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig) | 96 Hours | 0/77  3 Lots |
| **High Humidity High Temperature Reverse Bias (H3TRB)** | TA=85℃+/-2℃ RH=85%+/-5%  VR=80%VB(customer spec.)  DC Supply | 1000 Hours | 0/77  3 Lots |

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| **Test** | **Condition** | **Duration** | **Failure rate** |
| **Solderability (SD)** | Temperature of solder Pb free: POT=245±5℃  Solder immersion time=5±0.5 sec  Dipping depth= within 1.27mm of the body. | 1 Cycle | 0/10  3 Lots |
| **ESD - HBM** | 100 pF / 1.5 KΩ | 3 Cycles | 0/30  3 Lots |
| **ESD - MM** | 200pF / 0Ω | 3 Cycles | 0/30  3 Lots |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Part Numbers Affected:**



As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |